

IN THE CLAIMS:

1. (Original) A probe card electrically coupled to a plurality of contact terminals provided on a circuit under test for performing signal transmission between said circuit under test and an external semiconductor testing equipment, comprising:

a substrate;

a plurality of signal transmission paths formed on said substrate; and

a plurality of contactors formed on ends of said plurality of signal transmission paths on one side of said substrate, wherein said plurality of contactors are made of an amorphous material comprising a supercooled liquid phase region and contacted to said contact terminals provided on said circuit under test.

2. (Original) A probe card as claimed in claim 1, wherein said contactor is formed to be separated from said substrate.

3. (Previously Presented) A probe card as claimed in claim 1, wherein said contactor is extended to a predetermined direction from a surface of said substrate.

4. (Previously Presented) A probe card as claimed in claim 1, wherein said contactor has a vertical elasticity against a surface of said substrate.

5. (Previously Presented) A probe card as claimed in claim 1, wherein at least a portion of said signal transmission path near said end of it is made of the same amorphous material used for said contactor.

6. (Previously Presented) A probe card as claimed in claim 1 further comprising a grounding line, which is grounded, formed to be apart from and in parallel to said signal transmission path.

7. (Withdrawn) A probe card as claimed in claim 1 further comprising a low-resistance unit having lower resistance than that of said signal transmission path, said low-resistance unit being formed near said signal transmission path.

8. (Withdrawn) A probe card as claimed in claim 1, wherein said contactor comprises a contacting point made of a contact-point material on an end of it.

9. (Withdrawn) A probe as claimed in claim 1, wherein said contactor is coated with a metal material.

10. (Previously Presented) A probe card as claimed in claim 1 further comprising a voltage providing unit for providing a predetermined voltage, said voltage providing unit being provided on a backside of said one side of said substrate.

11. (Original) A probe card as claimed in claim 10, wherein said voltage providing unit is formed on an area other than areas of said backside of said substrate corresponding to areas of said one side of said substrate where said contactors are formed.

12. (Original) A probe card as claimed in claim 10, wherein  
said substrate is made of a dielectric material or semiconductor material,  
said signal transmission path, said substrate and said voltage providing unit form a microstrip line having a predetermined characteristic impedance.

13. (Withdrawn) A probe card as claimed in claim 1 further comprising a plurality of contactors made of an amorphous material having a supercooled liquid phase region, wherein said plurality of contactors are electrically coupled to said contactors formed on said one side of said substrate through said signal transmission paths and formed on a backside of said substrate.

14. - 24. (Cancelled)